

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Johnny Ch ng, et al.

Docket No.: TI-31614.1A

Serial No.: TBD

Examiner: TBD

Filed: Herewith

Art Unit: TBD

For: BGA Substrate Via Structure

Conf. No.: TBD

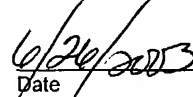
TRANSMITTAL OF FORMAL DRAWINGS

Commissioner For Patents  
Attn: Official Drafts Person  
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.

  
Elizabeth Austin

  
Date

Dear Sir:

Submitted herewith are 3 sheets of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

No fee is believed by Applicant to be due; however, the Commissioner is hereby authorized and requested to charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicants  
Reg. No.: 36,682

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653